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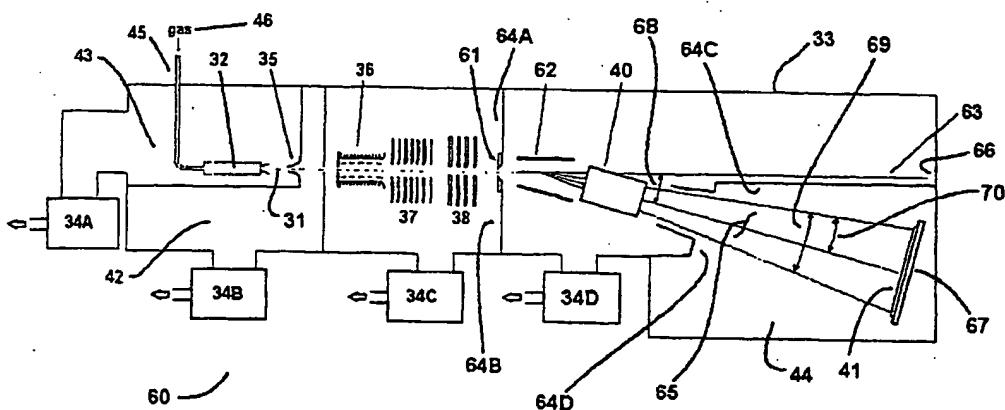
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(54) Title: ENHANCED ETCHING/SMOOTHING OF DIELECTRIC SURFACES



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(57) Abstract: A gas cluster ion beam (GCIB) etching apparatus having a system for producing a gas cluster ion beam utilized to controllably etch a substrate. The gas cluster ion beam is initially directed along a preselected longitudinal axis. A portion of the GCIB etching apparatus is operably connected to the beam producing system and contains the substrate to be etched when impacted by said gas cluster ion beam. The portion of the GCIB etching apparatus includes a system for directing the gas cluster ion beam in a direction offset from the preselected longitudinal axis while permitting unwanted ionizing radiation to remain directed along the longitudinal axis. A substrate holder is located within a portion of the GCIB etching apparatus for positioning the substrate in line with the offset gas cluster ion beam during the etching process, and the unwanted ionizing radiation being substantially prevented from impinging upon the substrate during the etching process.

ENHANCED ETCHING/SMOOTHING OF DIELECTRIC SURFACES

BACKGROUND OF THE INVENTION

5 This invention relates generally to the smoothing of dielectric surfaces, and, more particularly to the etching/smoothing of dielectric surfaces wherein it is desirable to avoid exposing such dielectric to the effects of ultraviolet radiation, X-ray radiation and/or ionizing
10 electromagnetic radiation.

As integrated circuit device sizes have been shrunk to create denser, more functional devices, the gate delays of the devices have typically become shorter and the devices have become faster. However, the corresponding shrinking of the
15 integrated circuits' interconnecting metal lines and of the inter-metal dielectric insulators, has resulted in increased signal propagation delays. These increasing interconnection propagation delays have generally resulted from the increased resistance of the thinner metal interconnect lines and the
20 increased capacitance that results from closer spacing of conductors and from the thinner insulating dielectric layers which are necessitated. This situation, which is well known in the integrated circuit development community, poses a barrier to continued successful increases in integrated
25 circuit density, speed, and functionality.

In order to continue shrinking integrated circuit devices while maintaining or improving their speeds, designers of integrated circuit interconnect are finding it necessary to reduce the resistivity of the metals used and to reduce the
30 inter-metal (both interline and interlayer) capacitances. This trend can be noted in the developing shift from the longstanding use of aluminum interconnect metal to the use of lower resistivity copper. It can also be noted in the developing shift from the use of SiO₂ as the dielectric
35 material of choice (having dielectric constant, k ≈ 3.9) towards the use of dielectric materials having a lower dielectric constants (low-k materials) in the range of 3>k>1.

In order for future generations of integrated circuits to meet their performance goals, the materials and methods for routine fabrication of low-k materials for inter-metal dielectric insulation must be developed. One example of an

5 interconnecting structure which is being developed to take advantage of lower resistivity metal conductors and low-k inter-metal dielectric materials is known in the semiconductor industry as "copper dual damascene interconnect."

Because of the critical nature of this problem for the
10 integrated circuit manufacturing community, a very large effort is being expended to identify and develop low-k materials and methods for their incorporation into the product process flow. In addition to low dielectric constant, there are many other requirements for suitable insulating materials.

15 These include low cost, high leakage resistance, mechanical strength, thermal stability, non-corrosiveness, compatible coefficient of expansion, ease of deposition, gap filling ability, appropriate etching characteristics, ability to act as a migration barrier, and numerous other desired
20 characteristics. No material appears to satisfy all requirements, and so the industry is examining tradeoffs between various possible materials.

One class of low-k materials that is of considerable interest is a family of fluorine-containing polymers generally
25 known as parylenes. These materials have been successfully applied for some time in a variety of industries where conformal dielectric coating of complex shapes has been required. At least two parylenes known as parylene-N and parylene-F have been discussed by R.S. List, et. al. in MRS
30 Bulletin, Oct., 1997, p.61. They show that these parylenes have properties that are considered favorable for use as potential low-k ($k < 2.5$) integrated circuit dielectric materials and methods have been devised (for example those taught in US Patent 5,879,808 - Wray, et. al.) for fabricating
35 them into the multi-level structures required separating circuit interconnection layers.

Historically, SiO_2 has been used as the primary dielectric material for silicon integrated circuits. A factor in it's

longstanding utility has been the ease and precision with which it can be etched into a desired patterns and thickness using wet chemistry etchants such as hydrofluoric acid and the like. As device geometries have become smaller, there has 5 been an increase in the use of dry etching techniques because of their tendency to be able to produce finer patterns. Most modern low-k dielectric materials including parylene have been generally understood to be best etched using dry etching methods such as plasma etching, ion etching, and the like, 10 rather than by wet etching.

A problem exists, however, in that plasma etching and other dry etching processes are known to sometimes leave a degree of damage on and beneath the etched surfaces. Furthermore, conventional dry etching processes (plasma 15 etching, reactive ion etching, conventional ion etching, sputter etching, and ion beam milling) all unavoidably expose the etched surface to electromagnetic radiation including ultraviolet wavelengths - because the substrate to be etched is directly exposed to radiation from the associated plasma.

20 Fluorine-containing polymers (fluoropolymers) such as parylene can react, upon exposure to ultraviolet of appropriate wavelengths, to liberate fluorine, which though chemically unbound may remain entrapped in the fluoropolymer matrix. Adjacent metal interconnect layers may eventually 25 react with the corrosive free fluorine, resulting in a shortened useful lifetime of the integrated circuit. This creates a potential integrated circuit device reliability problem.

There is a need for a dry etching technique capable of 30 efficiently producing uniformly homogeneous etching over large diameter (200 - 300 mm or larger) wafers without residual damage and without producing residual free fluorine in order to enable greater success in the application of fluoropolymers (such as parylenes) for use as inter-metal low-k dielectrics 35 in future integrated circuit generations.

The concept of using gas cluster ion beams (GCIB) for dry etching, cleaning, and smoothing of hard materials is known in the art and has been described by Deguchi, et.al in US patent

5,814,194. Because ionized clusters containing on the order of thousands of gas atoms or molecules may be formed and accelerated to modest energies on the order of a few thousands of electron volts, individual atoms or molecules in the
5 clusters each only have an average energy on the order of a few electron volts. It is known from the teachings of Yamada, US patent 5,459,326, that such individual atoms are not individually energetic enough to significantly penetrate a surface to cause the residual surface damage typically
10 associated with the other types of dry etching in which individual atoms have energies on the order of hundreds or thousands of electron volts. Nevertheless, the clusters themselves are sufficiently energetic (some thousands of electron volts) to effectively etch, smooth, or clean hard
15 surfaces.

An important consideration in the ion beam processing of surfaces covered by insulating films (as is the case when fluoropolymer films are deposited on semiconductor wafers) is the tendency for the charged beam to induce charging of the
20 surface being processed (etched, in this case). If sufficient charge is permitted to accumulate on the insulating surface without means for dissipation, the dielectric properties of the film may be exceeded and the film can be ruptured or otherwise permanently damaged by the electrical stress. This
25 problem is well known in ion beam processing such as ion implantation, ion milling, and GCIB processing. It is to be expected that means of limiting the surface charging of fluoropolymer films during GCIB etching must be provided if undesirable and harmful charging is to be avoided. When the
30 positive cluster ions strike the insulating film, they may transfer their charge to the film. The collision process also results in the liberation of secondary particles from the surface - surface atoms thus liberated result in the etching of the surface. The liberated secondary particles may be
35 electrons, neutral atoms, or charged atoms. Free electrons are much more mobile than free charged atoms (ions) and are likely to escape. Thus, the main tendency of the release of secondary particles is to increase the positive charging of

the surface. Such charging can produce damage to the insulating material and has prevented the successful prior application of ion cluster beam processing to some insulating surfaces.

5 It is therefore an object of this invention to provide a GCIB system capable of efficiently producing uniformly homogeneous etching over large diameter (200 - 300 mm or larger) substrates without residual damage and without producing residual free fluorine in order to enable greater
10 success in the application of fluoropolymers (such as parylenes) for use as inter-metal low-k dielectrics in future integrated circuit generations.

It is another object of this invention to provide a GCIB system which substantially eliminates the problems associated
15 with the production of undesirable ultraviolet and X-ray radiation.

It is a further object of this invention to provide a method for efficiently etching large diameter (200 - 300 mm or larger) substrates without residual damage due to electrical
20 charging or to deep surface penetration by light ions and without exposing the substrates to ionizing electromagnetic radiation.

It is still another object of this invention to provide a GCIB system which substantially eliminates the electrical
25 charging of an insulating surface to be etched.

SUMMARY OF THE INVENTION

The objects set forth above as well as further and other
30 objects and advantages of the present invention are achieved by the embodiments of the invention described hereinbelow.

This invention provides a dry etching gas cluster ion beam (GCIB) apparatus and process for, preferably, etching/smoothing fluoropolymer layers and thin films. The
35 process of this invention results in producing a smoother surface, a surface with less subsurface damage, a surface without charging damage to the fluoropolymer, and a surface without free fluorine impurities caused by ultraviolet or X-

ray radiation. The invention accomplishes this end by including means within a portion of a GCIB etching apparatus for directing the gas cluster ion beam in a direction offset from a preselected axis while permitting unwanted ionizing 5 radiation (ultraviolet, X-ray and electromagnetic radiation) to remain directed along the preselected axis. The substrate to be etched being positioned in line with the offset gas cluster ion beam. This invention, therefore, facilitates the successful and efficient application of fluoropolymer and 10 other fluorine bearing insulating dielectric materials to the problem of low-k dielectric insulation between conductors in integrated circuit interconnect systems. For a better understanding of the present invention, together with other and further objects thereof, reference is made to the 15 accompanying drawings and detailed description and its scope will be pointed out in the appended claims.

BRIEF DESCRIPTION OF THE DRAWINGS

20 Figure 1 is a prior art plasma etch or reactive ion etch configuration, showing exposure of the substrate to be etched to ultraviolet radiation generated in the plasma;

Figure 2 is a prior art ion milling configuration, showing exposure of the substrate to be etched to ultraviolet 25 radiation generated in the plasma in the ion source;

Figure 3 represents a prior art gas cluster ion beam processing system;

Figure 4 represents a gas cluster ion beam processing system of the present invention to avoid UV irradiation of the 30 substrate to be etched;

Figure 5 represents an alternate embodiment of the gas cluster ion beam processing system of the present invention to avoid UV irradiation of the substrate to be etched;

Figure 6 represents undesirable charging of a dielectric 35 layer occurring during gas cluster ion beam processing; and

Figure 7 represents a further preferred embodiment of the gas cluster ion beam processing system of this invention for

etching insulating surfaces without damage due to surface charging.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS

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- In order to better understand the present invention it is desirable to describe the prior art systems in which the substrate to be etched (also referred to as smoothed) is directly exposed to the radiation from the associated plasma
- 10 reference is made to Figures 1 and 2 of the drawings. For example, Figure 1 shows a plasma etch or reactive ion etch system 10 in which the substrate to be etched 11 rests on lower electrode 16. Low pressure gas which may be inert or reactive is introduced through gas port 14. A plasma 12 is
- 15 generated in the region between upper electrode 15 and lower electrode 16. Through action of the plasma 12, the substrate 11 is etched or reactively etched. Plasma 12 produces radiation including ultraviolet radiation. There is a direct line-of-sight path 13 for the ultraviolet radiation to travel
- 20 from the plasma 12 to the substrate 11. Although not shown in Figure 1, plasma etch or reactive ion etch equipment may sometimes use a ultraviolet emitting igniter to trigger plasma formation - in such cases radiation from the igniter may also strike the surface to be etched.
- 25 Figure 2 shows an ion milling system 20 having a Kaufman type or similar ion source 22 into which is introduced a low pressure gas through a gas port 23. A plasma 24 is generated within the source 22 and ions 26 are formed into a beam directed from source 22 to substrate 21 for etching substrate
- 30 21. The plasma 24 produces radiation including ultraviolet radiation. Because there exists a direct line-of-sight path 25 from the plasma 24 to the substrate 21 being etched, ultraviolet radiation from the plasma 24 strikes the substrate 21.
- 35 Figure 3 shows a typical configuration for a gas cluster ion beam processor 30. The processor is enclosed in a vacuum vessel 33 consisting of a source chamber 43 and a processing chamber 44. Although not required, it may sometimes be

desirable to also employ a differential vacuum pumping chamber 42 to help isolate the downstream regions from the higher pressure upstream regions. The interior of vacuum vessel 33 is maintained at a vacuum reduced pressure by vacuum pumps 34A, 34B, 34C, and 34D. A source gas 46 is introduced through gas feed tube 45. Gas clusters 31 are formed by creating a supersonic jet of source gas through a properly shaped nozzle 32 into the source chamber 43 which is at a substantially reduced pressure. Cooling resulting from the expansion causes the gas to condense into clusters of from several to several thousand atoms or molecules. A gas skimmer aperture 35 is used to separate the gas products that have not been converted into a cluster jet from the cluster jet so as to minimize pressure in the downstream regions where such higher pressures would be detrimental (e.g., ionizer 36, accelerator high voltage electrodes 38, and processing chamber 44). Suitable source gases 46 are, for example, argon, other inert gases, oxygen, nitrogen, oxygen bearing gases such as carbon dioxide, and nitrogen bearing gases. Inert gases etch the substrate surfaces by mechanical action. Because, during cluster impact, transiently high temperatures and pressures obtain, chemical reactions are facilitated. Therefore, reactive gases like oxygen or oxygen bearing gases are additionally effective because surface chemical reactions can accelerate the mechanical etching effect. Of course, mixtures of inert gases with reactive gases are also possible. Fluoropolymers are hydrocarbons and so will be readily oxidized under cluster impact conditions. Nitrogen is also known to decompose parylene at high temperatures. Oxygen, nitrogen, and oxygen or nitrogen bearing gases are likely to be effective GCIB etchants for fluoropolymers.

After the cluster jet has been formed, the clusters 31 are ionized in an ionizer 36. The ionizer 36 is typically an electron impact ionizer that produces thermoelectrons from one or more incandescent filaments and accelerates and directs the electrons causing them to collide with the gas clusters 31 in the gas cluster jet where it passes through the ionizer 36. The electron impact ejects electrons from the clusters,

causing the clusters to become positively ionized. A set of suitably biased high voltage lens electrodes 37 extracts the cluster ions from the ionizer and focuses them to form a gas cluster ion beam. Another set of high voltage accelerator 5 electrodes 38 accelerates the beam to a desired energy, typically from 1 keV to several tens of keV. The accelerated beam is directed at a substrate 41 for GCIB processing. Not shown, but sometimes utilized, is a mass selector for selecting clusters of a certain mass or within a certain range 10 of masses. Such mass selector can be, for example, a weak transverse magnetic field for deflecting monomer ions and other light ions (e.g., those cluster ions of ten or fewer atoms or molecules) out of the beam and passing more massive cluster ions.

15 Since the fluoropolymer etching application contemplates the etching of large diameter wafers with spatially uniform results, a scanning system 47 is desirable in order to uniformly scan the gas cluster ion beam (GCIB) across large areas to produce spatially homogeneous results. Two pairs of 20 orthogonally oriented electrostatic scan plates 39 and 40 make up scanning system 47, and having suitable beam scanning voltage waveforms imposed can be utilized to produce a raster or other scanning pattern across the desired area.

There are three problems that interfere with the 25 straightforward application of GCIB processing as shown in Figure 3 to the etching of fluoropolymers. The first problem results from the possible production of a small amount of ultraviolet ionizing radiation in the ionizer region and the potential for that radiation to reach the substrate being 30 processed where it could produce the detrimental effects described in the discussion of the prior art. The ionizer section, as has been mentioned, typically contains incandescent filaments and creates a region populated with accelerated electrons, low energy secondary electrons, and 35 positive ions, both monomers and clusters of all sizes. Neutral gas molecules are also present. It is possible that glow discharges and other plasma effects can take place, potentially producing undesirable ultraviolet (UV) radiation.

Furthermore, the filaments for producing the thermoelectrons produce light including a UV component. In the system shown in Figure 3, there is line-of-sight from the ionizer region to the substrate processing chamber, where the fluoropolymer 5 containing substrate to be etched is disposed. As discussed above, that UV component, even though small, could leave free fluorine in the etched material with the attendant ill effects previously described.

The second problem has to do with the production of low 10 energy ionizing X-radiation (X-rays) in the ionizer, lens, and accelerator regions and the potential for that radiation to reach the substrate being processed where it can produce the same detrimental effects ascribed to UV radiation in the discussion of the prior art, namely the formation of corrosive 15 free fluorine in the fluoropolymer. X-rays are produced by the bremsstrahlung process when electrons are attracted to and strike positively charged electrodes. The presence of electrodes charged at potentials of up to a few tens of kilovolts in the ionizer, lens, and accelerator regions of the 20 GCIB process machine, and the availability of free electron. Free electrons are generated in the ionizer, in the beam by collision of the beam with residual gas in the vacuum, and by secondary electron emission from the vacuum enclosure inner walls when stray ions strike the walls.

25 The third problem results from the fact that, while etching with GCIB, the bombardment of insulating films such as parylenes by the positively charged ions in a GCIB may induce electrical charging of the insulating surface being etched. As described hereinbefore, such charging can rupture or 30 otherwise damage the insulating film.

The preferred embodiments of the present invention provide a system and technique for substantially eliminating or ameliorating these three problems.

One way of eliminating the undesirable effects of UV on 35 fluoropolymers is to eliminate the UV entirely. Since the ionizer is a potential source of UV in a GCIB process machine, one could eliminate the source of UV by ionizing the beam in a way that did not produce any glow discharge and did not have

an incandescent filament. This could be done by ionizing the beam using a radioactive beta source as the source of ionizing electrons.

Alternatively, ionization could be performed by using a 5 laser or other intense light source to photo-ionize the clusters. By directing the laser or light source so as to avoid purposeful transmission of any UV toward the substrate to be etched, the undesirable effects of UV on the substrate to be etched due to the light source can be minimized.

10 A preferred embodiment of the present invention, however, utilizes a conventional electron impact ionizer that may produce a small amount of UV, but takes advantage of the beam-nature of the GCIB process to eliminate line-of-sight from the potential UV forming region to the substrate processing 15 region. This system of eliminating UV from striking the substrate being etched is preferred because it has the added advantage that it can also prevent X-rays generated in the ionizer, lens, or accelerator regions from reaching the substrate being etched by simultaneously eliminating line-of-sight from the X-ray forming regions to the substrate 20 processing region.

Figure 4 shows one of several possible embodiments of the invention utilizing of a basic GCIB apparatus configuration that can virtually completely eliminate the possibility of UV 25 or X-rays reaching the substrate 41 to be etched. In this embodiment, a fixed (DC) deflection voltage has been added to the beam scanning voltage waveforms at the Y-scan deflection plates 62 to impose a fixed offset angle 68 between the initial beam path and the path of the scanned GCIB 65, the 30 offset being imposed in the region between the scan plates 62. At scan plates 62, in addition to being deflected in the amount of offset angle 68, the GCIB also is scanned through a scanning angle 69. One half of the scan angle 69 is referred to as the scan half angle 70. The UV radiation and X-rays are 35 not responsive to the electrostatic field between scan plates 62 and continue in a straight line 63 to an impact point 66 in a region now separated from the substrate 41 processing region by the GCIB fixed angular deflection. As shown, collimator 61

and baffle arrangements 64A, 64B, 64C, and 64D can be added in combination with the angular beam offset to further reduce the likelihood of stray reflections directing even a small amount of UV to the substrate 41 processing area. It is especially 5 important that the impact point 66 of the undeflected UV and X-ray radiation be baffled from the substrate 41 processing area, and in the example shown in Figure 4, baffle 64C serves this purpose. It is also important that the scanned GCIB 65 enter the baffled region and be enclosed in the baffle and 10 thus separated from the straight line path 63. Substrate 41 is held and positioned in the path of the scanned beam 65 and away from the path of the undeflected UV and X-ray radiation by substrate holder 67. If the baffles 64A, 64B, 64C and 64D and the collimator 61 are formed of or have a layer of a 15 material which absorbs X-rays, then they are also effective to prevent X-rays from reaching the substrate 41. The selection of X-ray absorbing materials (such as heavy metals, e.g., lead) and the determination of the necessary thickness of such material (typically a few millimeters in this case) is well known to those who practice the art of X-ray shielding.

Figure 4 further shows, for purposes of example, but not for limitation, a fixed angular deflection or offset angle 68 of the GCIB of approximately 15 degrees from the initial beam trajectory. However, it is apparent that any deflection angle 25 larger than the scan half-angle 70 is potentially adequate to separate the GCIB from the electromagnetic radiation beam (UV or X-ray), provided that the undesired UV beam can be adequately collimated. Although we have illustrated the case where ionization is by electron impact, it can be appreciated 30 that method and system of this invention can also be used to separate a GICB from stray UV resulting from the use of a photo-ionizing light source.

As shown in Figure 4, an electrostatic deflection element 62 is used to separate the GCIB from the potential UV beam. 35 Of course, other schemes for deflecting the GCIB from the potential UV beam could also be used. For example, a sector magnet could be used to deflect the beam while allowing the UV and X-rays to pass undeflected. In general we consider an

electrostatic form of deflection to be the preferred method for several reasons:

1. The GCIB will normally contain cluster ions of a range of masses. Although as mentioned earlier, mass selection filters are known, it is not general practice to select only cluster ions of one specific mass or of a very narrow range of masses. To do so would result in the discarding of a large number of cluster ions of the rejected masses resulting in a much lower mass flux, which would result in a reduced etch rate. For this reason, it is advantageous to retain all cluster ions of greater than a predetermined mass. The ionizer typically produces or is typically adjusted to produce a preponderance of cluster ions that are singly ionized - one electron has been removed. All ions are accelerated by falling through an electrostatic potential field of a predetermined voltage, typically some few to few tens of kilovolts. Thus the great majority of gas cluster ions have the same charge (+1) and the same energy ($E=V_a$, where V_a is the acceleration potential), but where they have a wide range of velocities due to the fact that they have a continuous range of masses from several to several thousands of atomic or molecular weights. Thus the great majority of the cluster ions have the same electrostatic deflection stiffness, but have widely differing magnetic deflection stiffnesses. A GCIB having a range of cluster sizes responds uniformly to an electrostatic deflection element, but a magnetic deflection element will also tend to disperse the masses, which in general is undesirable.
2. Readily controllable electrostatic elements can generally be manufactured for a lower cost than similarly controllable magnetic elements.
3. Power consumption of electrostatic elements is generally lower than that of magnetic elements.
4. Electrostatic fields are readily contained by the metal containers usually employed as vacuum vessels, while magnetic fields are more difficult to shield and when unshielded can introduce workplace hazards and can interfere with sensitive equipment.

Still referring to Figure 4, the electrostatic deflection angular deflection function has been shown combined with an electrostatic scanning function in a pair of electrostatic scanning/deflecting plates 62, which replace the simple 5 scanning-only electrostatic scanning plates 39 used in the prior art shown in Figure 3. This is convenient and efficient. However it is readily appreciated that such configuration is not the only one that can be effective and that there are alternate embodiments of this invention. For 10 example, an alternate embodiment is shown in Figure 5 which uses an "electrostatic mirror" element 74 to introduce a 90 degree deflection from the initial trajectory of the GCIB, while permitting any potential UV beam 63 to travel undeflected.

15 The electrostatic mirror element 74 is a plate and grid arranged and electrically biased so as to reflect the GCIB at an approximately 90 degree angle from the path of the beam 63 of ultraviolet or X-ray electromagnetic radiation. The plate has a hole 76 to permit passage of any UV or X-ray beam 63 20 that may be present. The mirror power supply 75 applies a retarding potential greater than V_a , the beam acceleration potential. The grid and the negative side of the mirror power supply are grounded to the wall of the vacuum vessel 33. A potential advantage of this arrangement is that it shortens 25 the overall length of the apparatus. A potential disadvantage is that the grid of the mirror 74 is struck by the GCIB and could experience sputter erosion. It can be appreciated that alternative means of deflecting and baffling so as to separate the GCIB from the possible UV beam and to remove the substrate 30 to be etched from the influence of the UV may also be used within the spirit of the present invention.

Figure 6 schematically illustrates a stage in processing of a semiconductor substrate 41. A fluorocarbon dielectric layer 97 on top of previously processed conductive layer 98 is 35 being smoothed by GCIB processing. The substrate 41 is disposed on a substrate holder 67 that is grounded and, which mechanically supports the substrate 41 during processing. The substrate 41 is grounded by the holder 67. Charge from the

bombarding scanned GCIB 65 is transferred to surface of the fluorocarbon dielectric layer 97. Electrons tend to flow from ground through the substrate holder 67, the substrate 41, and the conductive layer 98 on the substrate 41 in order to

5 neutralize the positive charges arriving with the gas cluster ions 96 in the scanned GCIB 65. This induces electrical stress in the fluorocarbon dielectric layer 97. Charge building across the dielectric 97 can stress it and may rupture the dielectric layer and discharge. To be certain of

10 high yield production of semiconductor devices, it is necessary to avoid the dielectric-stressing and electrical discharge problem illustrated in Figure 6. In order to eliminate the problem of electrical charging of the low-k dielectric films during processing with the positive ion

15 cluster beam, it is necessary to make available a source of available electrons to the dielectric surface so that they may continuously neutralize the surface to prevent accumulation of a harmful charge across the dielectric layer 97.

This may be accomplished in any of several ways. A source of

20 thermoelectrons (e.g. a hot filament) may be placed in the vicinity of the substrate to be etched. A source of low energy secondary electrons generated from collision of an accelerated beam of electrons with a surface in the vicinity of the substrate to be etched may be used. A plasma bridge

25 source of low energy electrons may be conveyed to the substrate to be etched by a neutral plasma in the substrate processing area. All of these methods are viable methods of neutralizing any positive charge that would otherwise tend to accumulate on the surface of a fluoropolymer dielectric film

30 being etched by a GCIB method. Without such measures, damage from charging is likely to result in such negative consequences that the otherwise useful and novel process might be severely impaired in usefulness. Figure 7 shows further embodiment of the GCIB system of this invention similar to

35 that shown in Figure 4 for UV free etching of fluoropolymer dielectric layers including modifications to minimize the effects of surface charging due to the use of positive cluster ions as the etching means. The substrate processing region is

surrounded with a Faraday enclosure 81 having a suppressor ring electrode 87 at the beam entrance opening of the Faraday enclosure 81. The suppressor ring electrode 87 is negatively biased with respect to the Faraday enclosure 81 by suppressor power supply 82 so as to permit entrance of the cluster ions 65 with minimal influence, but yet also prevent the exit of electrons, retaining all secondary electrons in the Faraday enclosure where they may be returned to the substrate 41.

Additionally, an active electron gun 85 powered by filament power supply 83 and anode power supply 84 is attached to the side-wall of the Faraday enclosure 81. The gun 85 is configured and biased to project a beam of primary electrons 88 to the opposite wall of the Faraday enclosure 81. The primary electron beam 88 induces the emission of low energy secondary electrons 89 from the Faraday enclosure wall. These low energy electrons 89 may flow to the substrate 41 as required to minimize positive charging due to arrival of the positive cluster ions 65. In some cases it may be desirable to control the amount of etching that occurs by measuring the total amount of positive gas cluster ions that strike the substrate 41. In such a case, a lead 86 from the Faraday enclosure 81 conducts charge to an integrator 90 that integrates the charge to provide an indication of etch process progress.

Although the invention has been described with respect to various embodiments, it should be realized this invention is also capable of a wide variety of further and other embodiments within the spirit and scope of the appended claims.

30

What is claimed is:

CLAIMS

1. A gas cluster ion beam (GCIB) etching apparatus comprising:

a system for producing a gas cluster ion beam utilized to controllably etch a substrate, said gas cluster ion beam initially being directed along a preselected longitudinal axis;

a portion of the GCIB etching apparatus being operably connected to said beam producing system, said portion containing the substrate to be etched when the substrate is impacted by said gas cluster ion beam;

said portion of the GCIB etching apparatus including means for directing said gas cluster ion beam in a direction offset from said preselected longitudinal axis while permitting unwanted ionizing radiation to remain directed along said longitudinal axis; and

means within said portion of the GCIB etching apparatus for positioning the substrate in line with said offset gas cluster ion beam;

wherein said unwanted ionizing radiation is substantially prevented from impinging upon the substrate during the etching process.

2. A GCIB etching apparatus as defined in claim 1 wherein said unwanted ionizing radiation contains UV radiation.

3. A GCIB etching apparatus as defined in claim 1 wherein said unwanted ionizing radiation contains X-ray radiation.

4. A GCIB etching apparatus as defined in claim 1 wherein said unwanted ionizing radiation contains both UV and X-ray radiation.

5. A GCIB etching apparatus as defined in claim 1 wherein said unwanted ionizing radiation is electromagnetic radiation.

6. A GCIB etching apparatus as defined in claim 1 wherein said means for directing said gas cluster ion beam comprises means for providing an electrostatic field which deflects said gas cluster ion beam toward the substrate.
7. A GCIB etching apparatus as defined in claim 6 further comprising a baffle at least partially encompassing the substrate.
8. A GCIB etching apparatus as defined in claim 7 wherein said baffle includes an entrance portion for permitting said offset gas cluster ion beam to pass onto the substrate.
9. A GCIB etching apparatus as defined in claim 7 further comprises a collimator in combination with an additional baffle for assisting in the prevention of said unwanted ionizing radiation from reaching the substrate.
10. A GCIB etching apparatus as defined in claim 8 wherein said baffle comprises material which is capable of absorbing X-ray radiation.
11. A GCIB etching apparatus as defined in claim 8 wherein said collimator comprises an aperture located within said additional baffle.
12. A GCIB etching apparatus as defined in claim 1 further comprising a scanning system which is capable of preselectively scanning said gas cluster ion beam through a preselected scan angle and wherein said offset gas cluster ion beam is offset at an angle larger than half said preselected scan angle.
13. A GCIB etching apparatus as defined in claim 1 wherein said offset gas cluster ion beam is offset from said preselected longitudinal axis at an angle of approximately 15 degrees.

14. A GCIB etching apparatus as defined in claim 1 wherein said means for directing said gas cluster ion beam comprises a reflective element assembly which deflects said gas cluster ion beam toward the substrate.
15. A GCIB etching apparatus as defined in claim 14 wherein said reflective element assembly comprises an electrostatic mirror.
16. A GCIB etching apparatus as defined in claim 15 wherein said electrostatic mirror further comprises means for permitting said unwanted ionizing radiation to pass therethrough.
17. A GCIB etching apparatus as defined in claim 16 wherein said reflective element assembly further comprises a power supply.
18. A GCIB etching apparatus as defined in claim 1 further comprising means for providing excess electrons to a surface of the substrate.
19. A GCIB etching apparatus as defined in claim 1 further comprising means for minimizing effects of surface charging on said substrate.
20. A GCIB etching apparatus as defined in claim 19 wherein said means for minimizing effects of surface charging on said substrate comprises a Faraday enclosure at least partially surrounding the substrate.
21. A GCIB etching apparatus as defined in claim 1 wherein the substrate contains a fluoropolymer component.
22. A method of etching a dielectric with gas cluster ion beam (GCIB) comprising the steps of:
providing a gas cluster ion beam;

separating the gas cluster ion beam from any unwanted ionizing radiation;

directing the gas cluster ion beam at a substrate to be etched during an etching process; and

further protecting the substrate from exposure to the unwanted ionizing radiation during the etching process.

23. A method of etching a dielectric with gas cluster ion beam as defined in claim 22 further comprising the step of:

providing a source of excess electrons during the etching process to prevent undesirable charging of the substrate surface.

24. A method of etching a dielectric with gas cluster ion beam as defined in claim 22 further comprising the step of:

providing baffles around at least a portion of the substrate.

25. A method of etching a dielectric with gas cluster ion beam as defined in claim 22 wherein said unwanted ionizing radiation contains UV radiation.

26. A method of etching a dielectric with gas cluster ion beam as defined in claim 22 wherein said unwanted ionizing radiation contains X-ray radiation.

27. A method of etching a dielectric with gas cluster ion beam as defined in claim 26 further comprising the step of:

providing an X-ray absorbing material to said baffle.

28. A method of etching a dielectric with gas cluster ion beam as defined in claim 22 wherein said unwanted ionizing radiation contains both UV and X-ray radiation.

29. A method of etching a dielectric with gas cluster ion beam as defined in claim 22 wherein said unwanted ionizing radiation is electromagnetic radiation.

30. A gas cluster ion beam (GCIB) etching apparatus comprising:

a system for producing a gas cluster ion beam utilized to controllably etch a substrate, said gas cluster ion beam initially being directed along a first axis;

a portion of the GCIB etching apparatus being operably connected to said beam producing system, said portion containing the substrate to be etched when the substrate is impacted by said gas cluster ion beam;

said portion of the GCIB etching apparatus including means for directing said gas cluster ion beam along a second axis in a direction offset from said first axis while permitting unwanted ionizing radiation to remain directed along said first axis; and

means within said portion of the GCIB etching apparatus for positioning the substrate in line with said offset gas cluster ion beam;

wherein said unwanted ionizing radiation is substantially prevented from impinging upon the substrate during the etching process.

31. A GCIB etching apparatus as defined in claim 30 wherein said unwanted ionizing radiation contains UV radiation.

32. A GCIB etching apparatus as defined in claim 30 wherein said unwanted ionizing radiation contains X-ray radiation.

33. A GCIB etching apparatus as defined in claim 30 wherein said unwanted ionizing radiation contains both UV and X-ray radiation.

34. A GCIB etching apparatus as defined in claim 30 wherein said unwanted ionizing radiation is electromagnetic radiation.

35. A GCIB etching apparatus as defined in claim 30 wherein said means for directing said gas cluster ion beam along said second axis comprises means for providing an electrostatic

field which deflects said gas cluster ion beam toward the substrate.

36. A GCIB etching apparatus as defined in claim 35 further comprising a baffle at least partially encompassing the substrate.

37. A GCIB etching apparatus as defined in claim 36 wherein said baffle includes an entrance portion for permitting said offset gas cluster ion beam to pass onto the substrate.

38. A GCIB etching apparatus as defined in claim 36 further comprising a collimator in combination with an additional baffle for assisting in the prevention of said unwanted ionizing radiation from reaching the substrate.

39. A GCIB etching apparatus as defined in claim 37 wherein said baffle comprises material which is capable of absorbing X-ray radiation.

40. A GCIB etching apparatus as defined in claim 37 wherein said collimator comprises an aperture located within said additional baffle.

41. A GCIB etching apparatus as defined in claim 30 further comprising a scanning system which is capable of scanning said gas cluster ion beam through a scan angle and wherein said offset gas cluster ion beam is offset at an angle larger than half said scan angle.

42. A GCIB etching apparatus as defined in claim 30 wherein said offset gas cluster ion beam is offset from said first axis at an angle of approximately 15 degrees.

43. A GCIB etching apparatus as defined in claim 30 wherein said means for directing said gas cluster ion beam comprises a reflective element assembly which deflects said gas cluster ion beam toward the substrate.

44. A GCIB etching apparatus as defined in claim 43 wherein said reflective element assembly comprises an electrostatic mirror.
45. A GCIB etching apparatus as defined in claim 44 wherein said electrostatic mirror further comprises means for permitting said unwanted ionizing radiation to pass therethrough.
46. A GCIB etching apparatus as defined in claim 45 wherein said reflective element assembly further comprises a power supply.
47. A GCIB etching apparatus as defined in claim 30 further comprising means for providing excess electrons to a surface of the substrate.
48. A GCIB etching apparatus as defined in claim 30 further comprising means for minimizing effects of surface charging on said substrate.
49. A GCIB etching apparatus as defined in claim 48 wherein said means for minimizing effects of surface charging on said substrate comprises a Faraday enclosure at least partially surrounding the substrate.
50. A GCIB etching apparatus as defined in claim 30 wherein the substrate contains a fluoropolymer component.

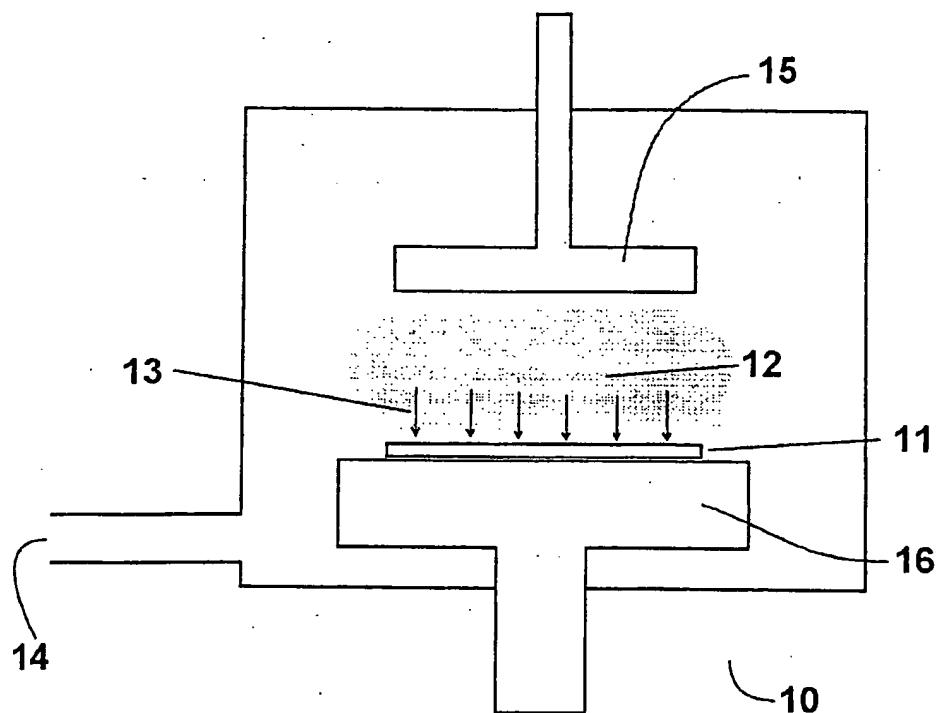


Figure 1. Prior Art

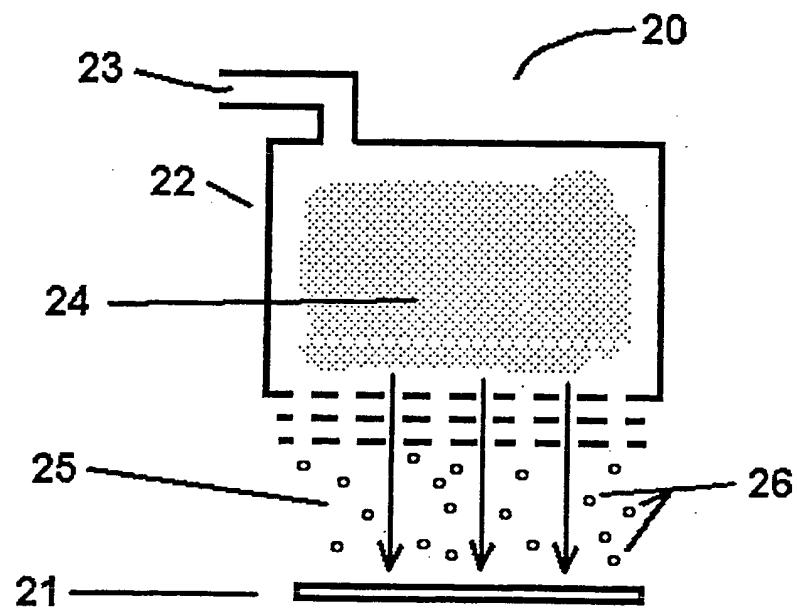


Figure 2. Prior Art

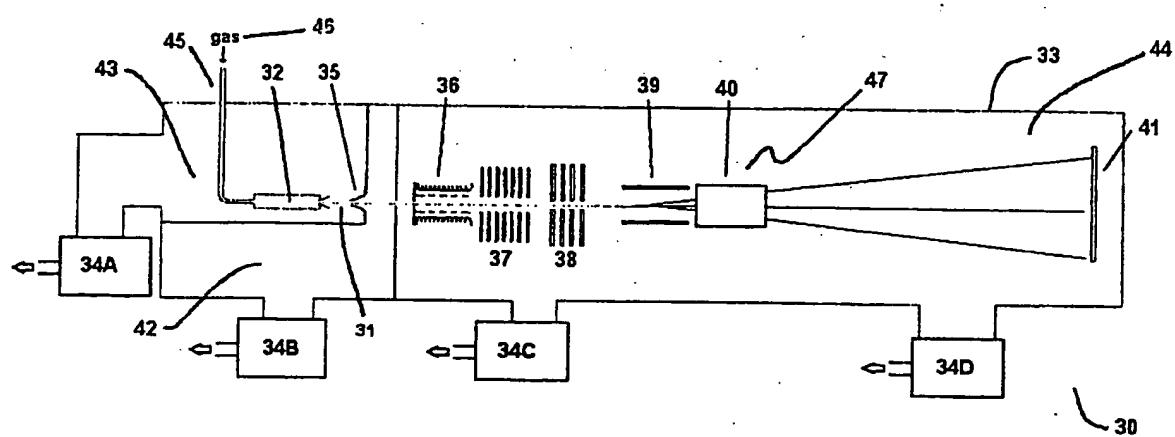


Figure 3. Prior Art

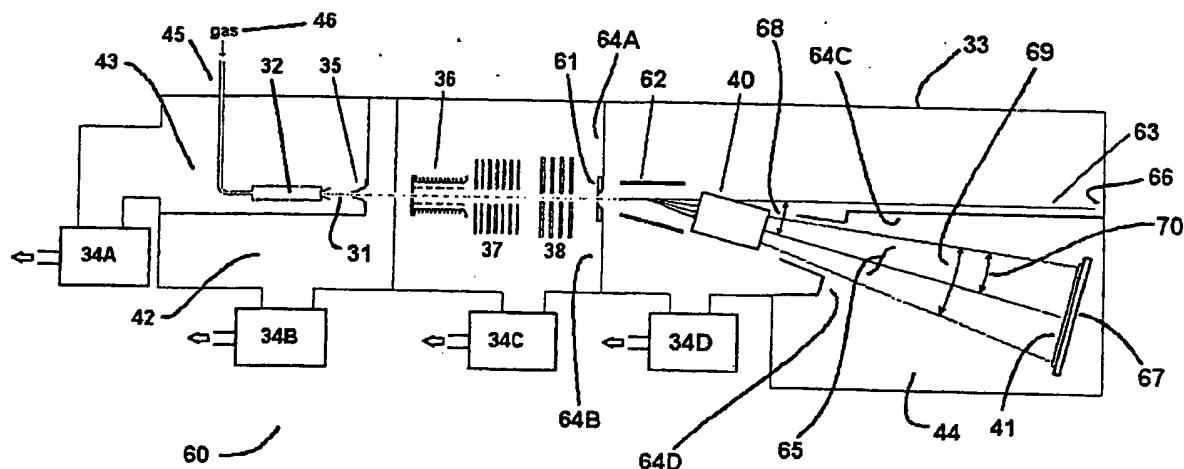


Figure 4.

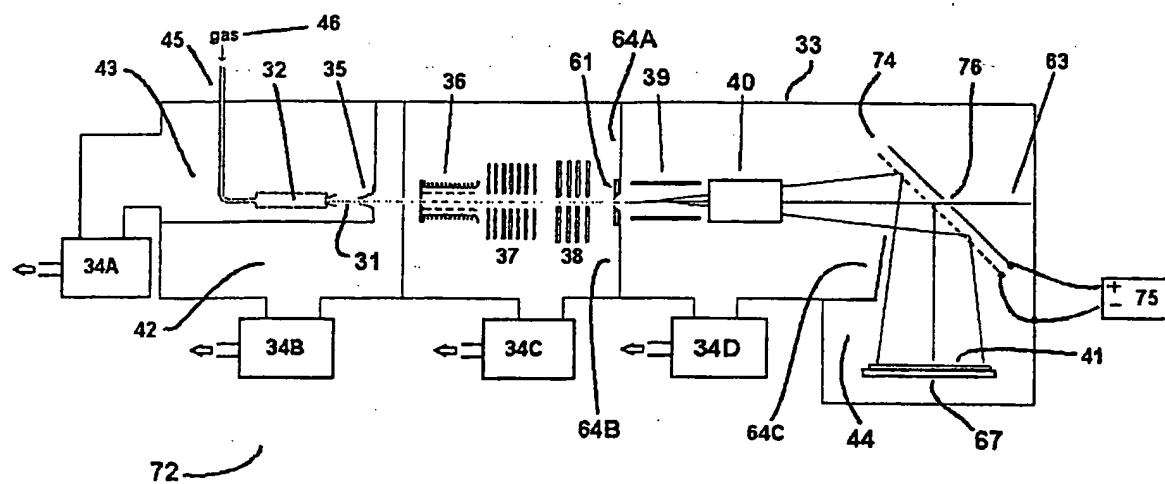


Figure 5.

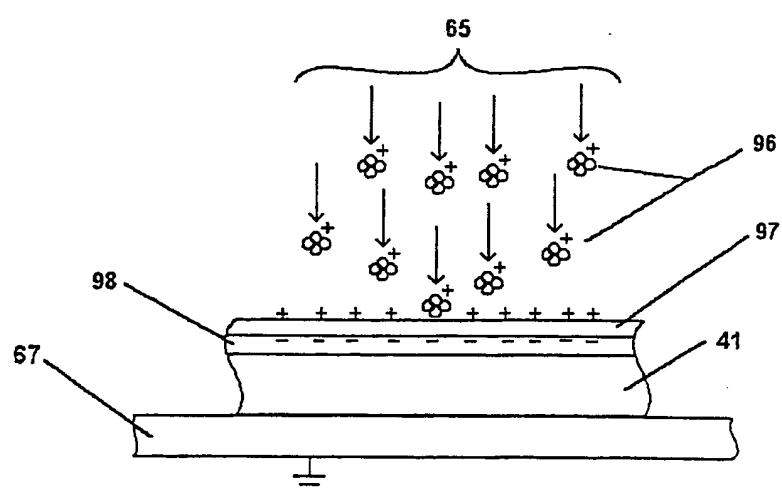


Figure 6.

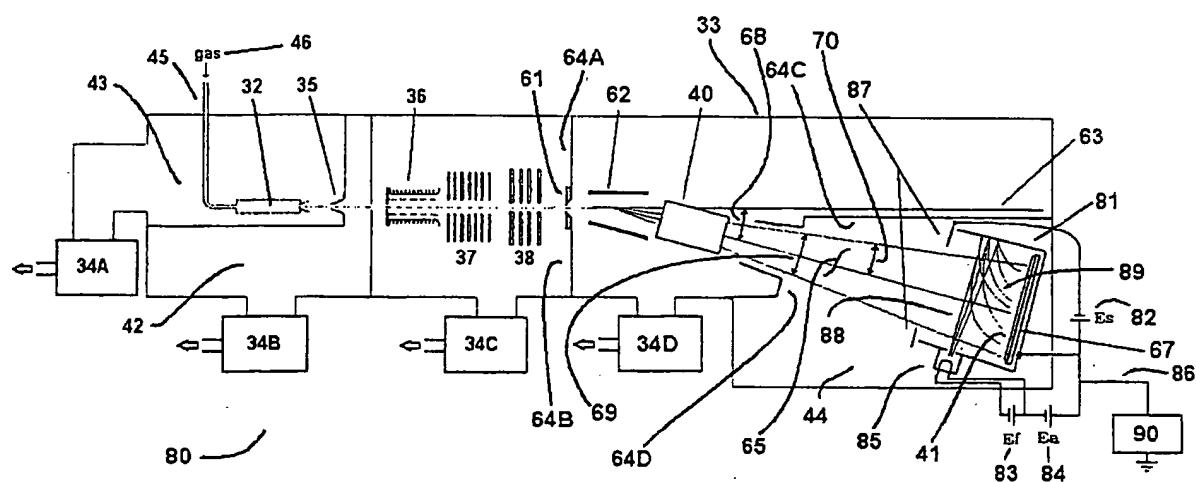


Figure 7.

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